



Material Content Data Sheet



Sales Product Name		IFX1040SJ		Issued		29. August 2013		
MA#		MA000981504						
Package		PG-DSO-8-16		Weight*		83.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.755	4.49	4.49	44896	44896
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8576	
wire	non noble metal	copper	7440-50-8	29.121	34.82	35.73	348214	357326
	noble metal	gold	7440-57-5	0.189	0.23	0.23	2260	2260
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1118
plastics	plastics	epoxy resin	-	4.299	5.14		51408	
	inorganic material	silicondioxide	60676-86-0	42.339	50.63	55.88	506260	558786
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9731	9731
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7775	7775
glue	plastics	acrylic resin	-	0.354	0.42		4230	
	noble metal	silver	7440-22-4	1.254	1.50	1.92	14996	19226
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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